Celanese
The chemistry inside innovation™

HOSTAFORM® C 2521 XAP®2

HOSTAFORM®

POM copolymer Stiff-flowing type for injection molding and extrusion with high impact toughness and good tracking resistance over a high range of temperature; good chemical resistance to solvents, fuel and strong alkalis as well as good hydrolysis resistance; high resistance to thermal and oxidative degradation. With reduced emissions especially for automotive interior application. Burning rate according to FMVSS 302 < 100 mm/min (1 mm thickness) Emission according to VDA 275 < 5 mg/kg.

Product information

Resin Identification	POM		ISO 1043
Part Marking Code	>POM<		ISO 11469

Rheological properties

Melt volume-flow rate	2.5	cm^3/10min	ISO 1133
Temperature	190	°C	
Load	2.16	kg	

Typical mechanical properties

Tensile modulus	2450	MPa	ISO 527-1/-2
Tensile stress at yield, 50mm/min	62	MPa	ISO 527-1/-2
Tensile strain at yield, 50mm/min	9	%	ISO 527-1/-2
Nominal strain at break	35	%	ISO 527-1/-2
Charpy impact strength, 23°C	250[P]	kJ/m^2	ISO 179/1eU
Charpy impact strength, -30°C	250	kJ/m^2	ISO 179/1eU
Charpy notched impact strength, 23°C	8.5	kJ/m^2	ISO 179/1eA
Charpy notched impact strength, -30°C	7	kJ/m^2	ISO 179/1eA
Poisson's ratio	0.38[C]		

[P]: Partial Break

[C]: Calculated

Thermal properties

Melting temperature, 10°C/min	166	°C	ISO 11357-1/-3
Temperature of deflection under load, 1.8 MPa	101	°C	ISO 75-1/-2
Coefficient of linear thermal expansion (CLTE), parallel	120	E-6/K	ISO 11359-1/-2
Coefficient of linear thermal expansion (CLTE), normal	120	E-6/K	ISO 11359-1/-2
Thermal conductivity of melt	0.155	W/(m K)	ISO 22007-2
Specific heat capacity of melt	2210	J/(kg K)	ISO 22007-4

Flammability

FMVSS Class	B		ISO 3795 (FMVSS 302)
Burning rate, Thickness 1 mm	41	mm/min	ISO 3795 (FMVSS 302)

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Electrical properties

Relative permittivity, 100Hz	4		IEC 62631-2-1
Relative permittivity, 1MHz	4		IEC 62631-2-1
Dissipation factor, 100Hz	15	E-4	IEC 62631-2-1
Dissipation factor, 1MHz	50	E-4	IEC 62631-2-1
Volume resistivity	1E12	Ohm.m	IEC 62631-3-1
Surface resistivity	1E14	Ohm	IEC 62631-3-2
Electric strength	35	kV/mm	IEC 60243-1
Comparative tracking index	600		IEC 60112

Physical/Other properties

Humidity absorption, 2mm	0.2	%	Sim. to ISO 62
Water absorption, 2mm	0.65	%	Sim. to ISO 62
Density	1410	kg/m^3	ISO 1183

Injection

Drying Recommended	no	
Drying Temperature	100	°C
Drying Time, Dehumidified Dryer	3 - 4	h
Processing Moisture Content	≤0.2	%
Melt Temperature Optimum	200	°C
Min. melt temperature	190	°C
Max. melt temperature	210	°C
Screw tangential speed	≤0.3	m/s
Mold Temperature Optimum	100	°C
Min. mould temperature	80	°C
Max. mould temperature	120	°C
Hold pressure range	60 - 120	MPa
Back pressure	4	MPa
Ejection temperature	140	°C

Characteristics

Processing	Injection Moulding, Film Extrusion, Extrusion, Sheet Extrusion, Other Extrusion, Blow Moulding
Delivery form	Pellets
Additives	Release agent
Special characteristics	Low emissions

Additional information

Injection molding

Preprocessing

To achive low emission values pre drying using a recirculating air dryer (100 to 120 °C / max. 40 mm layer / 3 to 6 hours) is recommended.

Max. Water content 0,1 %

Processing

Standard injection moulding machines with three phase (15 to 25 D) plasticating screws will fit.

Postprocessing

Conditioning e.g. moisturizing is not necessary.

Processing Notes

Pre-Drying

It is normally not necessary to dry HOSTAFORM. However, should there be surface moisture (condensate) on the molding compound as a result of incorrect storage, drying is required. A circulating air drying cabinet can be used for this purpose if the granul

Storage

The product can then be stored in standard conditions until processed.

Automotive

OEM	STANDARD	ADDITIONAL INFORMATION
Ford	WSK-M4D635-A1	
Li Auto	Q/LiA5310020	2021 (V2)
Mercedes-Benz	DBL5404	BQF
Mercedes-Benz	DBL5410	
Renault	No Spec, Special Part Approval, See Your CE Account Manager.	
VW Group	TL 524 76	Natural

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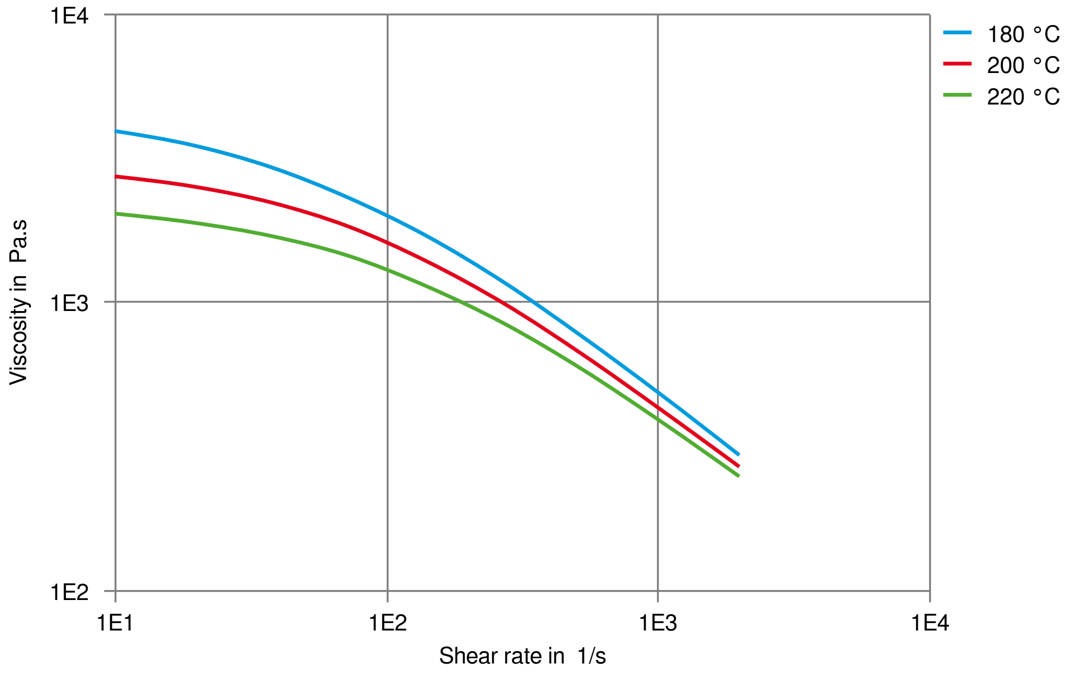
Viscosity-shear rate



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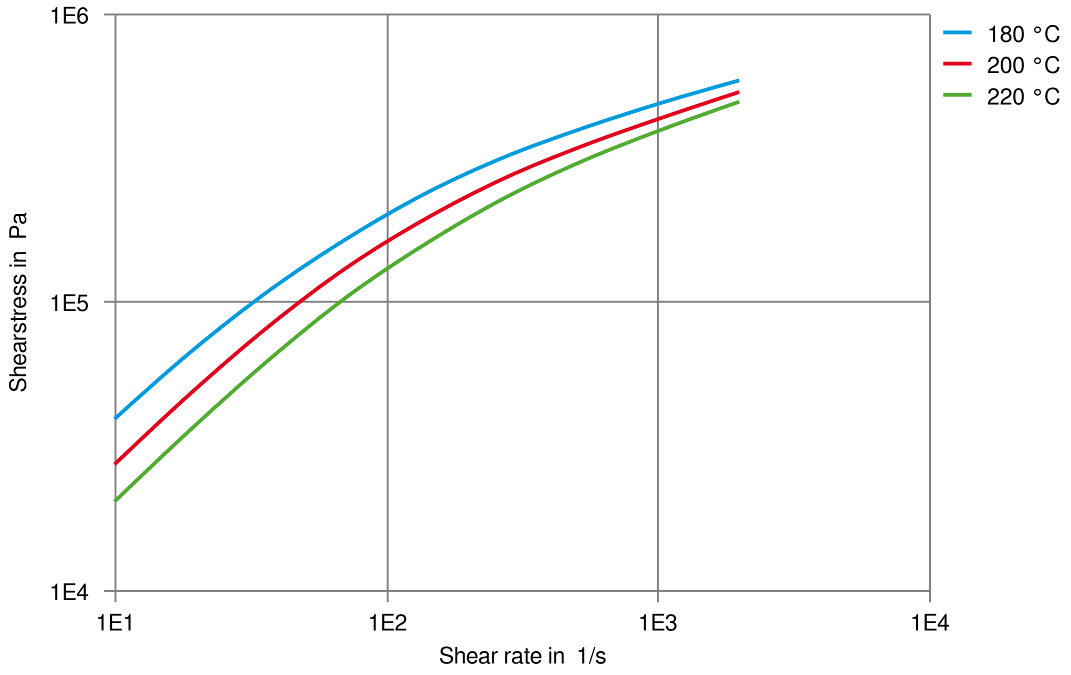
Shearstress-shear rate



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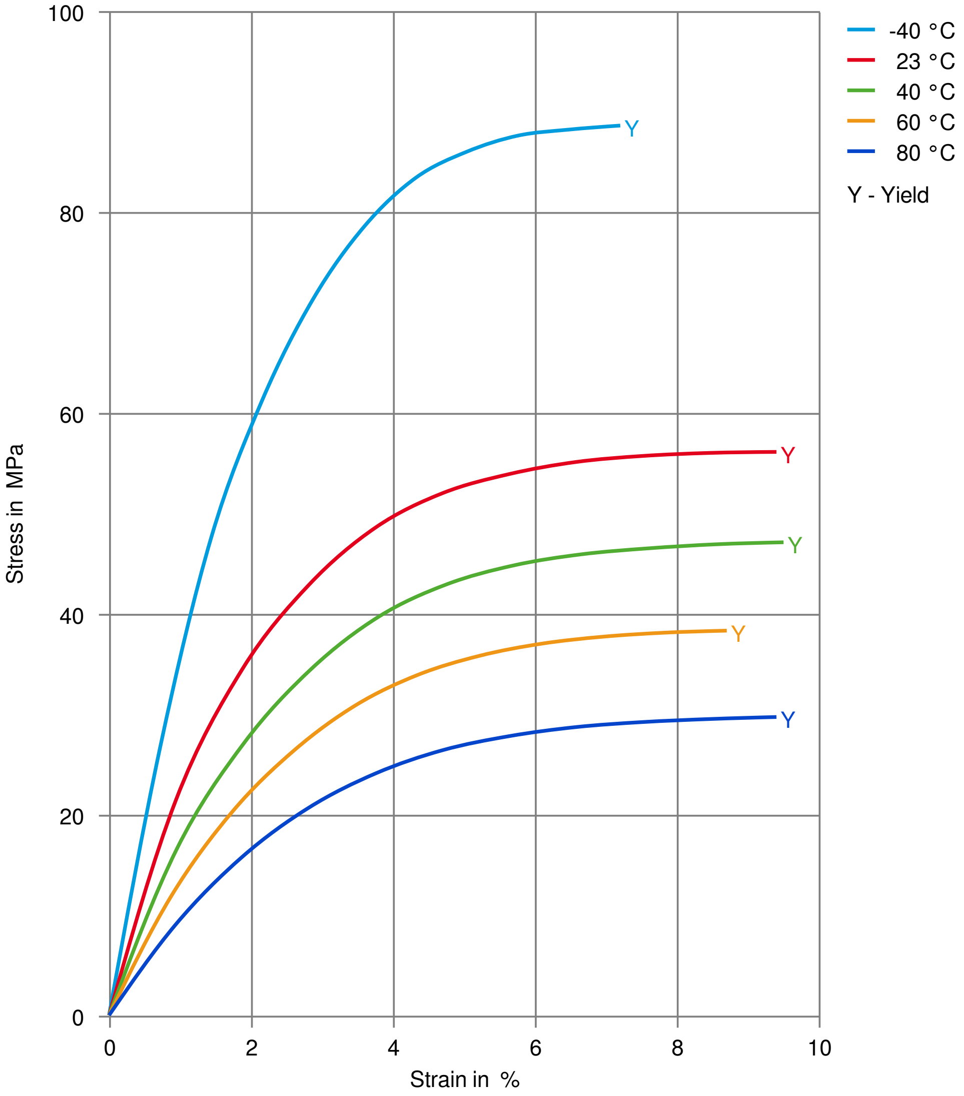
Stress-strain



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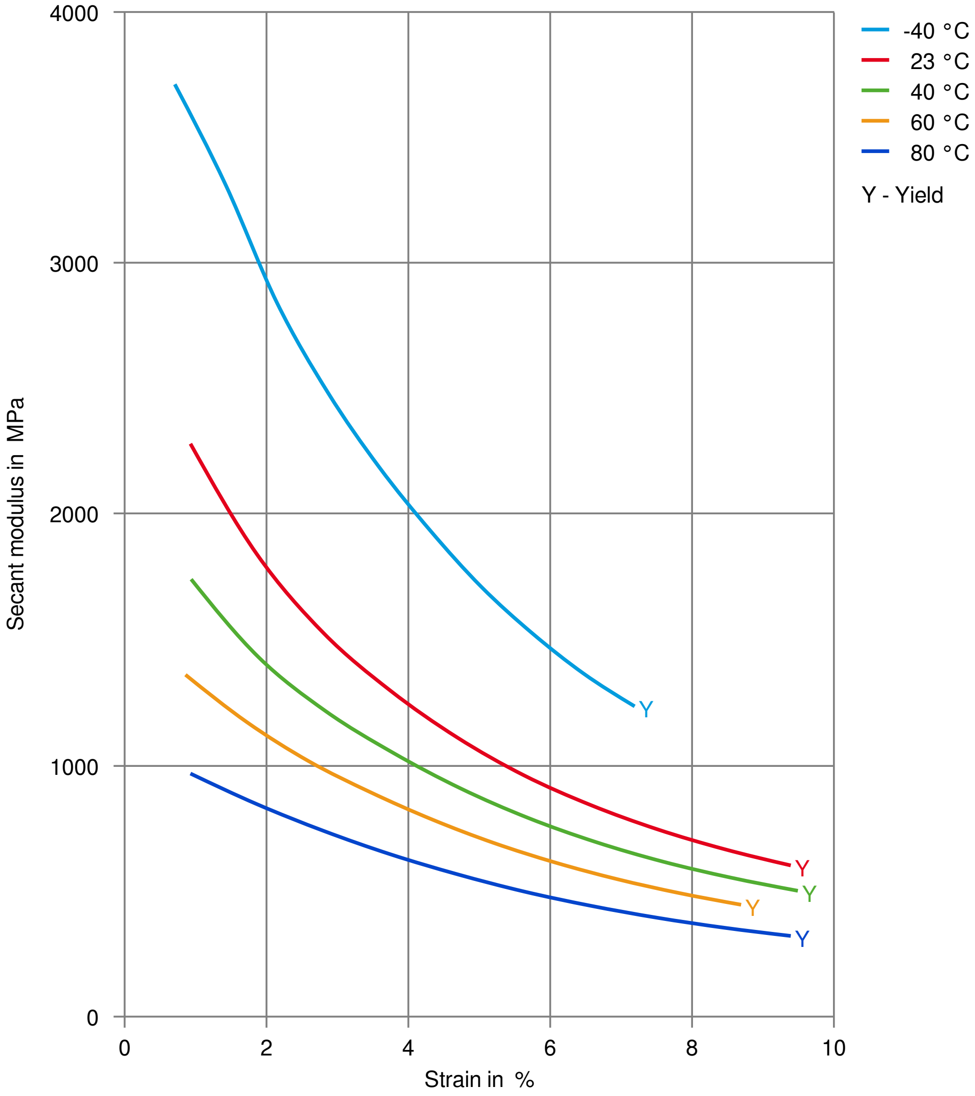
Secant modulus-strain



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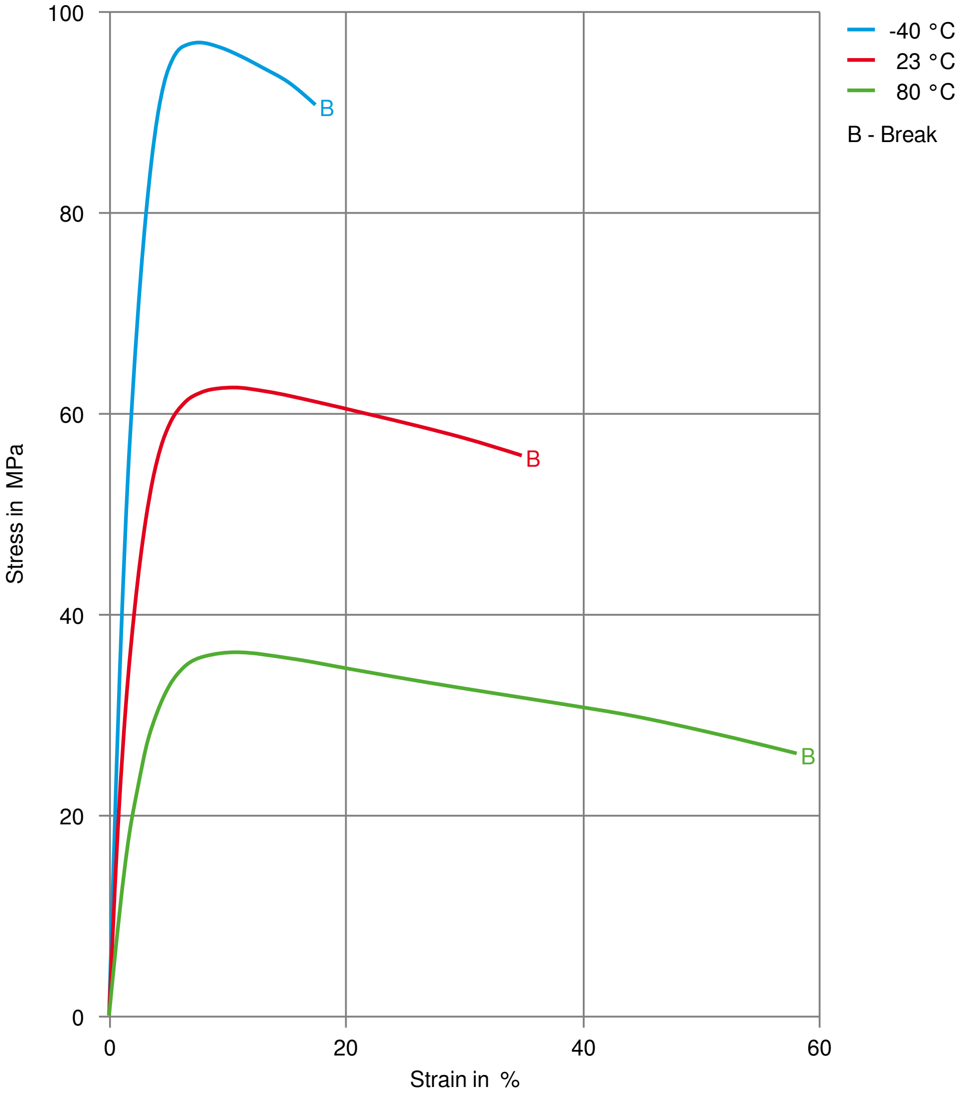
Stress-strain, 50mm/min



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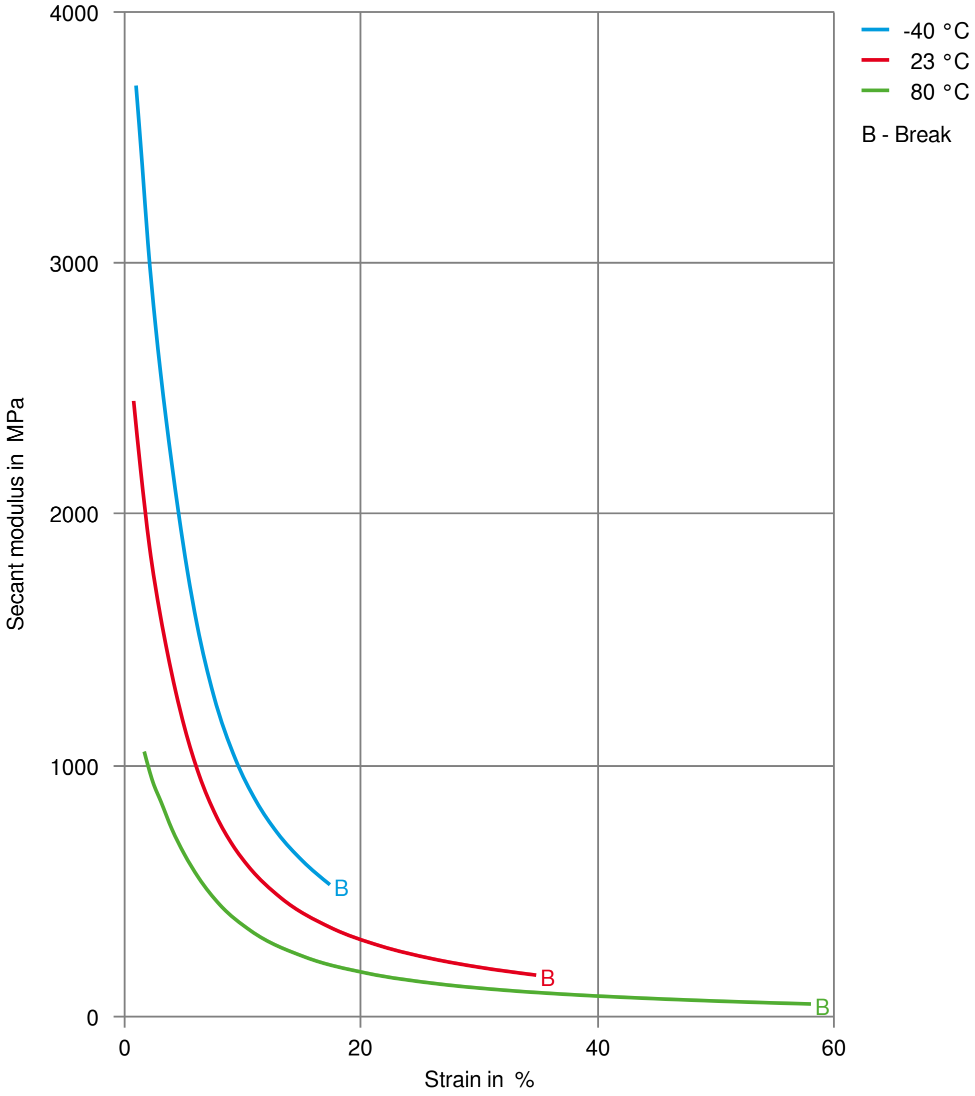
Secant modulus-strain, 50mm/min



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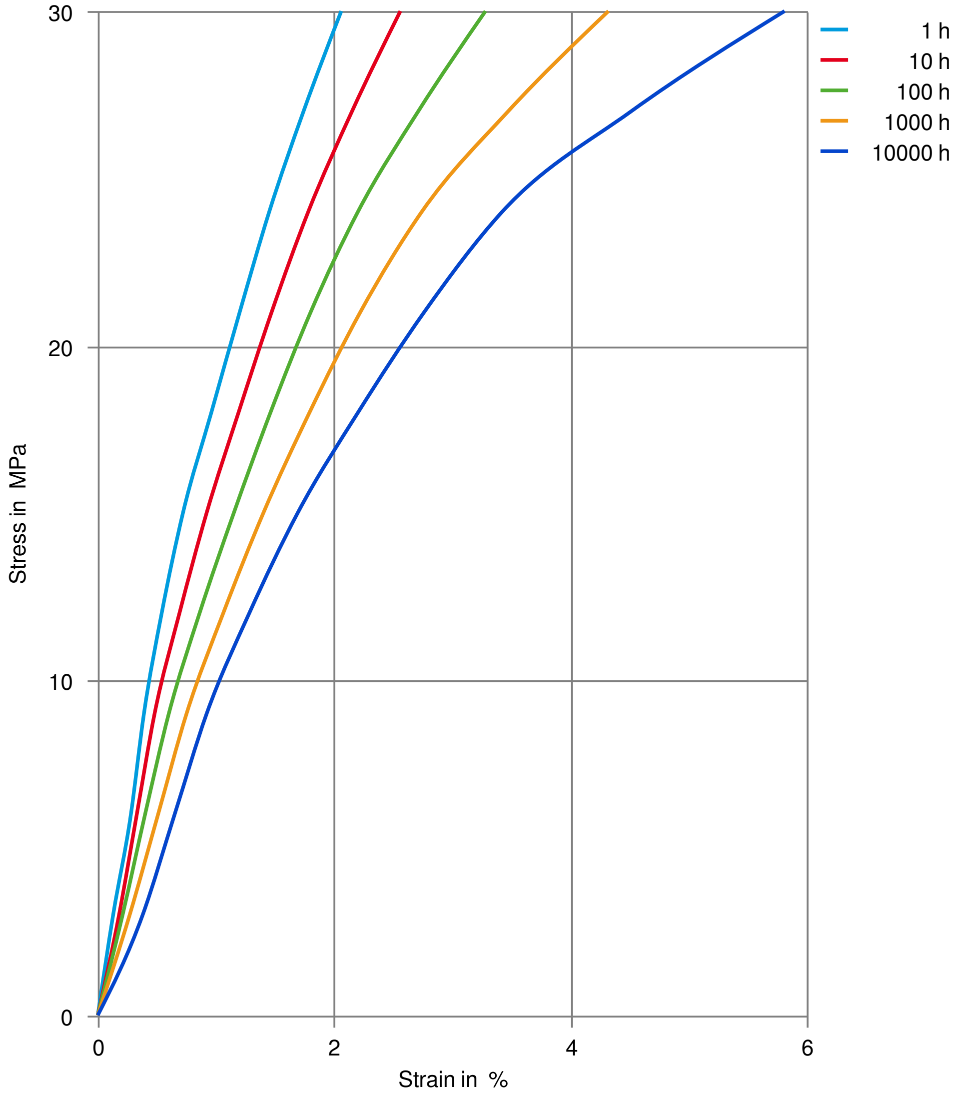
Stress-strain (isochronous) 23 °C



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Creep modulus-time 23 °C